

Notice of References Cited	Application/Control No. 09/826,383	Applicant(s)/Patent Under Reexamination SHIGEYOSHI YOSHIDA	
	Examiner Khiem D Nguyen	Art Unit 2823	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,738,240	05-2004	Ahn et al.	361/38
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NON-PATENT DOCUMENTS

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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